

Product Specification

产品规格书

Customer Name:

客户名称

Customer P/N:

客户料号

Product Name:

产品名称

晶体管光耦

Product P/N:

产品型号

MT-217-X(ABCD)

Sending Date:

制定日期

2026/04/15

| | | | | | | | | |
|---|-------------|--|------------------------------------|--------------|--------------------|---|--|--|
| <input type="checkbox"/> Technical Reference 技术参考 | | | <input type="checkbox"/> Sample 样品 | | | <input checked="" type="checkbox"/> Mass Product 量产供货 | | |
| Customer approval 客户审核 | | | Supplier approval 供方审核 | | | | | |
| Approved 核准 | Audit 确认 | Confirmation 制作 | Approved 核准 | Audit 确认 | Confirmation 制作 | | | |
| <input type="checkbox"/> Qualified 接受 | | <input type="checkbox"/> Disqualified 不接受 | | Date: 日期: | | | | |



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE DEVICES

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Photocoupler

Model No.: MT-217-X(ABCD)

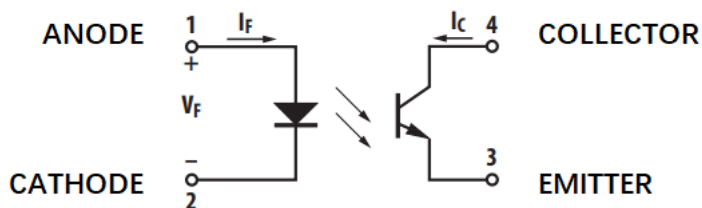
Features:

- Current transfer ratio (50%~600% at $I_F=5\text{mA}$; $V_{ce}=5\text{V}$)
- High input-output isolation voltage($V_{iso}= 3750\text{Vrms}$)
- SSOP-4 Package
- ESD pass (HBM8000V/MM2000V)
- MSL class1
- Safety approval
UL 1577
VDE
- RoHS compliance

Applications:

- Hybrid substrates that require high density mounting
- Programmable controllers
- System appliances, measuring instruments

Functional Diagram



Absolute Maximum Ratings

(Ta=25°C)

| | Parameter | Symbol | Rating | Unit |
|--------|-----------------------------|-----------|----------|-----------|
| Input | Forward Current | I_F | 50 | mA |
| | Reverse Voltage | V_R | 6 | V |
| | Power Dissipation | P | 70 | mW |
| Output | Collector - Emitter Voltage | V_{CEO} | 80 | V |
| | Emitter - Collector Voltage | V_{ECO} | 7 | V |
| | Collector Current | I_C | 50 | mA |
| | Collector Power Dissipation | P_C | 150 | mW |
| | Total Power Dissipation | P_{tot} | 200 | mW |
| *1 | Isolation Voltage | V_{iso} | 3000 | V_{rms} |
| | Operating Temperature | T_{opr} | -55~+110 | °C |
| | Storage Temperature | T_{stg} | -55~+150 | °C |
| *2 | Soldering Temperature | T_{sol} | 260 | °C |

*1: AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side
- (2) The isolation voltage tester with zero-cross circuit shall be used
- (3) The waveform of applied voltage shall be a sine wave

*2: For 10 Seconds

Electrical / Optical Characteristics (Ta=25°C)

| | Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------|--------------------------------------|---------------|--|--------------------|--------------------|------|----------|
| Input | Forward Voltage | V_F | $I_F=20mA$ | - | 1.2 | 1.4 | V |
| | Reverse Current | I_R | $V_R=4V$ | - | - | 10 | uA |
| | Terminal Capacitance | C_t | $V=0, f=1KHz$ | - | 30 | 250 | pF |
| Output | Collector Dark Current | I_{CEO} | $V_{CE}=50V, I_F=0$ | | | 100 | nA |
| | Collector-Emitter Breakdown Voltage | BV_{CEO} | $I_C=0.1mA, I_F=0$ | 80 | - | - | V |
| | Emitter-Collector Breakdown Voltage | BV_{ECO} | $I_E=10\mu A, I_F=0$ | 7 | - | - | V |
| TRANSFER CHARACTERISTICS | Collector Current | I_C | $I_F=5mA, V_{CE}=5V$ | 2.5 | - | 30 | mA |
| | *Current Transfer Ratio | CTR | $I_F=5mA, V_{CE}=5V$ | 50 | - | 600 | % |
| | Collector-Emitter Saturation Voltage | $V_{CE(SAT)}$ | $I_F=8mA, I_C=2.4mA$ | - | - | 0.4 | V |
| | Isolation Resistance | R_{iso} | DC500V, 40 ~ 60% R.H. | 5×10^{10} | 1×10^{11} | - | Ω |
| | Floating Capacitance | C_f | $V=0, f=1MHz$ | - | 0.6 | 1 | pF |
| | Response Time (Rise) | T_r | $V_{CE}=10V, I_C=2mA$ $RL=100\Omega, f=100Hz$ | - | 2 | 18 | us |
| | Response Time (Fall) | T_f | | - | 3 | 18 | us |
| | Turn-On Time | T_{on} | | - | 3 | - | us |
| Turn-Off Time | T_{off} | - | | 3 | - | us | |

* $CTR = \frac{I_C}{I_F} \times 100\%$

| CTR Rank | Min | Max | Condition |
|---------------|-----|-----|----------------------|
| A | 80 | 160 | $I_F=5mA; V_{ce}=5V$ |
| B | 130 | 260 | $I_F=5mA; V_{ce}=5V$ |
| C | 200 | 400 | $I_F=5mA; V_{ce}=5V$ |
| D | 300 | 600 | $I_F=5mA; V_{ce}=5V$ |
| None Or Other | 50 | 600 | $I_F=5mA; V_{ce}=5V$ |

CHARACTERISTICS CURVES

Figure 1. Collector Power Dissipation vs. Ambient Temperature

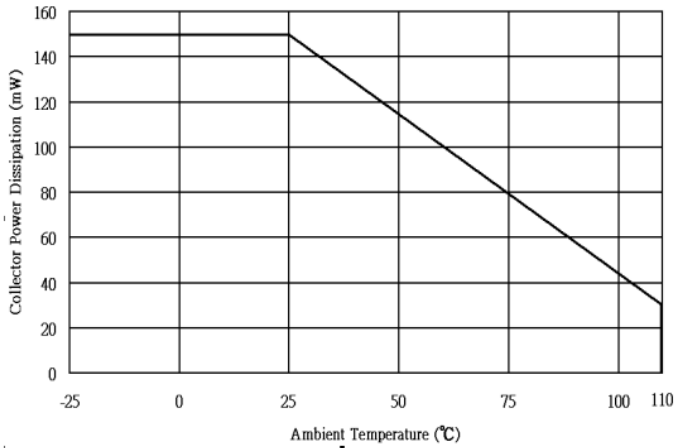


Figure 2. Forward Current vs. Ambient Temperature

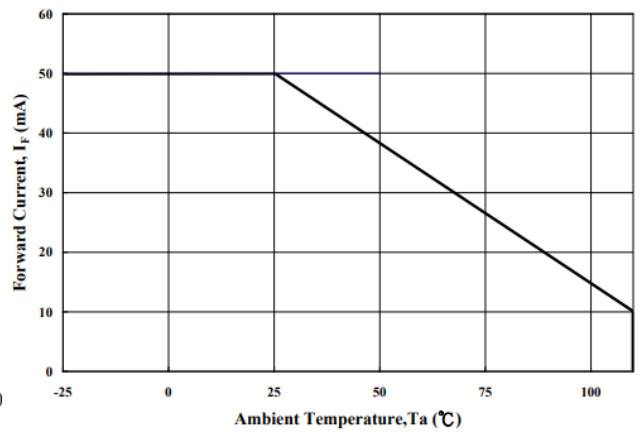


Figure 3. Forward Current vs. Forward Voltage

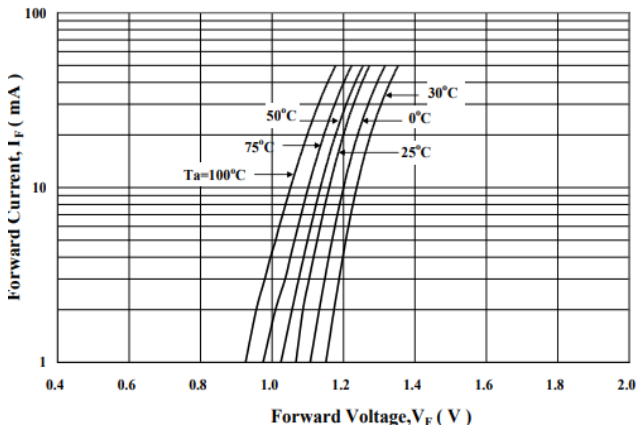


Figure 4. Forward Voltage Temperature Coefficient vs. Forward Current

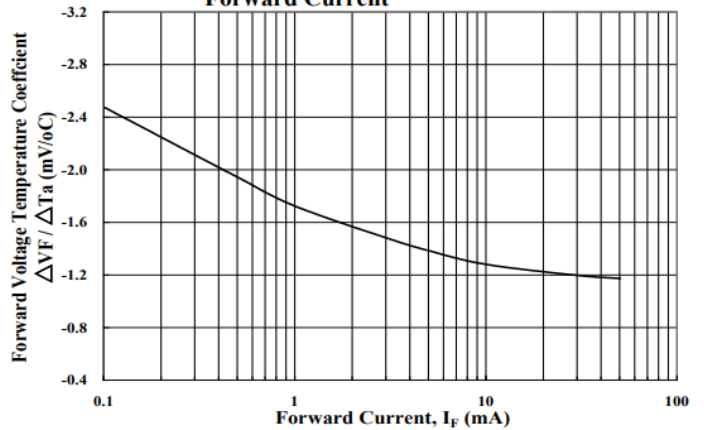


Figure 5. Pulse Forward Current vs. Duty Cycle Ratio

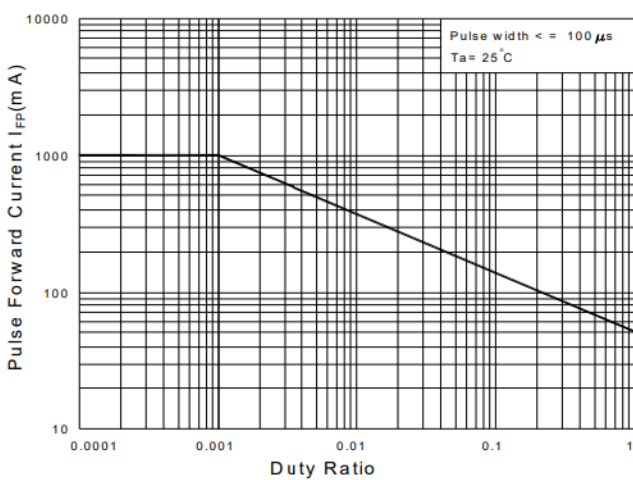


Figure 6. Pulse Forward Current vs. Pulse Forward Voltage

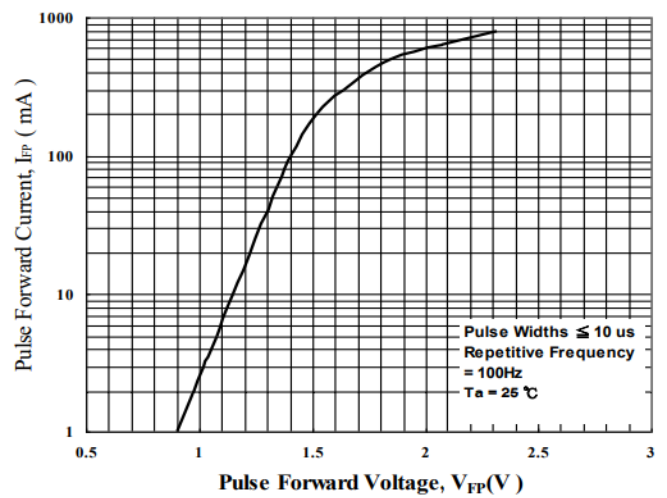


Figure 7. Collector-Emitter Saturation Voltage vs. Forward Current

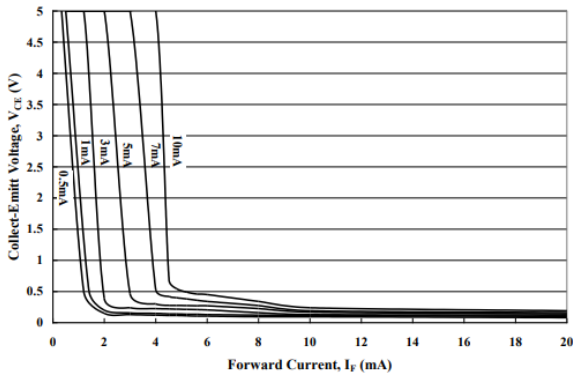


Figure 8. Collector Current vs. Collector-Emitter Voltage

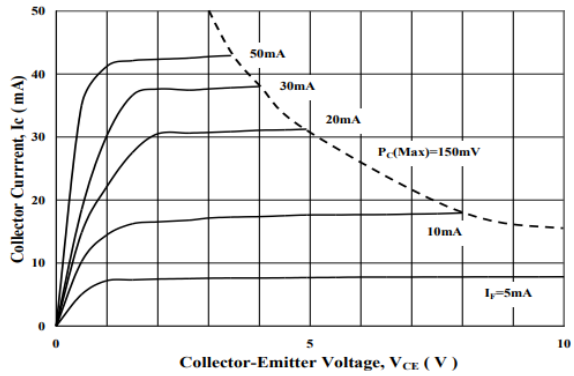


Figure 9. Collector Current vs. Small Collector-Emitter Voltage

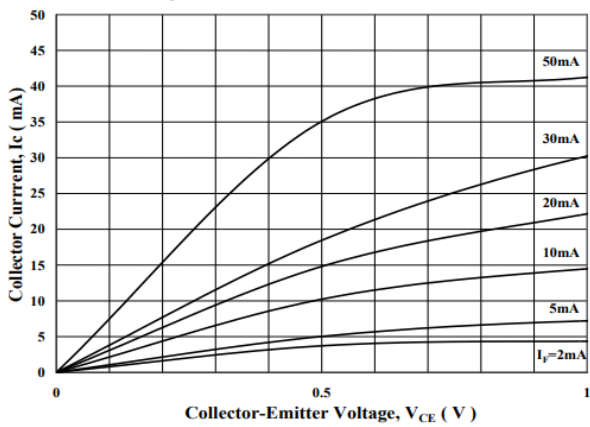


Figure 10. Collector Current vs. Forward Current

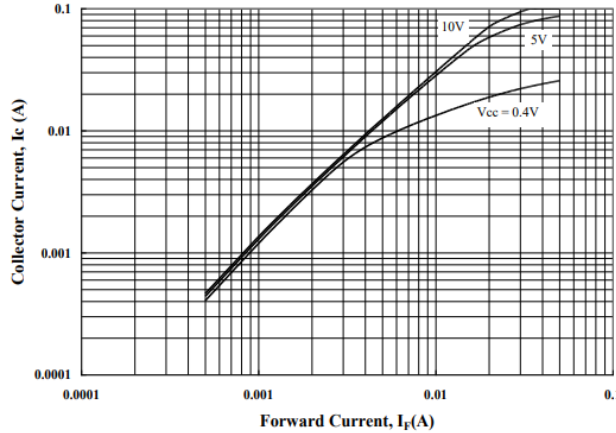


Figure 11. Collector Dark Current vs. Ambient Temperature

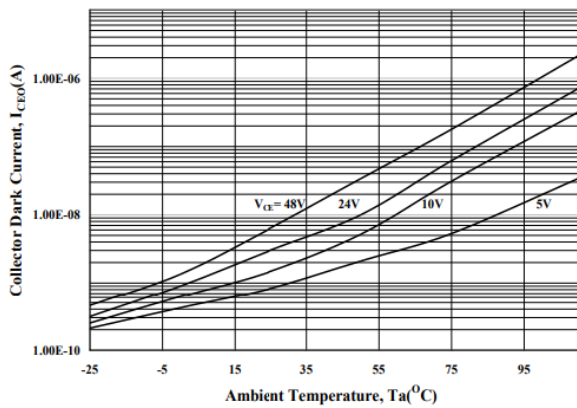


Figure 12. Current Transfer Ratio vs. Forward Current

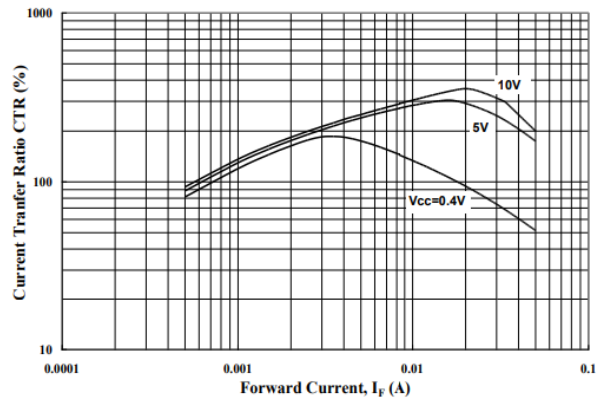


Figure 13. Collector-Emitter Saturation Voltage vs. Ambient Temperature

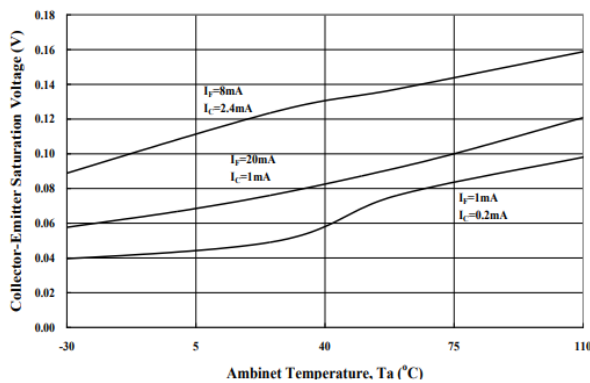


Figure 14. Collector Current vs. Ambient Temperature

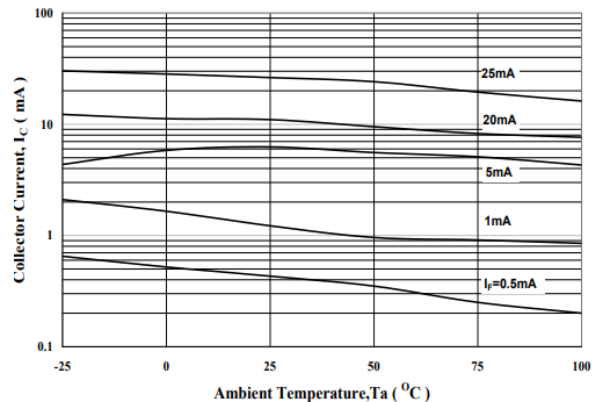


Figure 15. Switching Time vs. Load Resistance

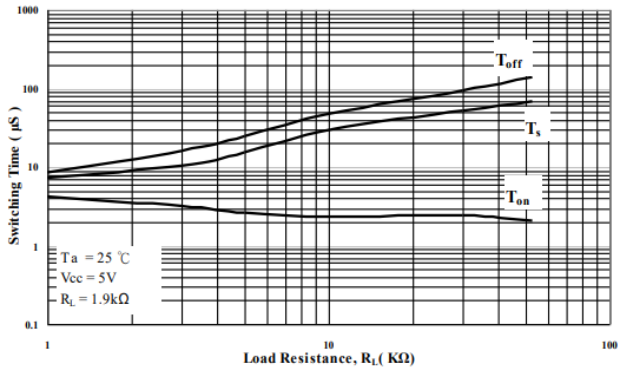


Figure 16. Switching Time vs. Ambient Temperature

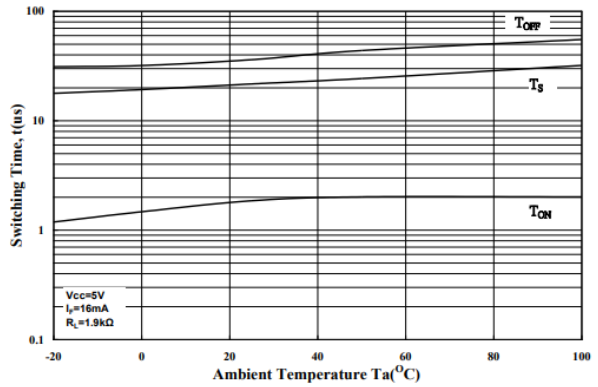
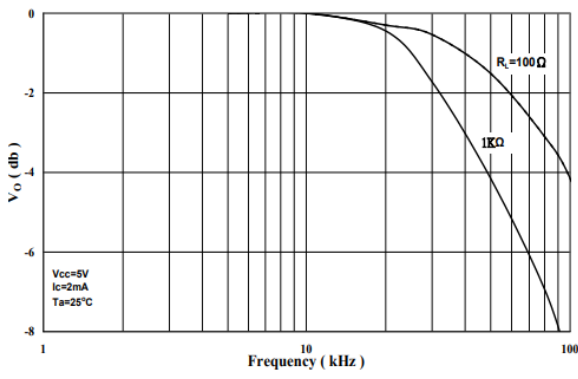
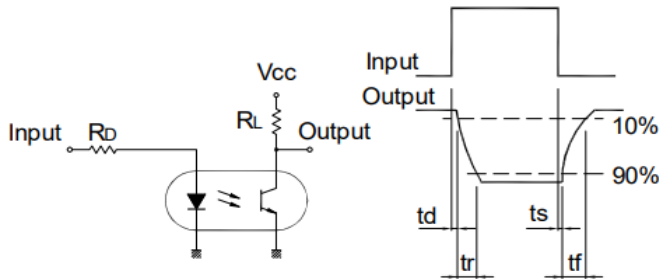


Figure 17. Frequency Response



Test Circuit for Response Time



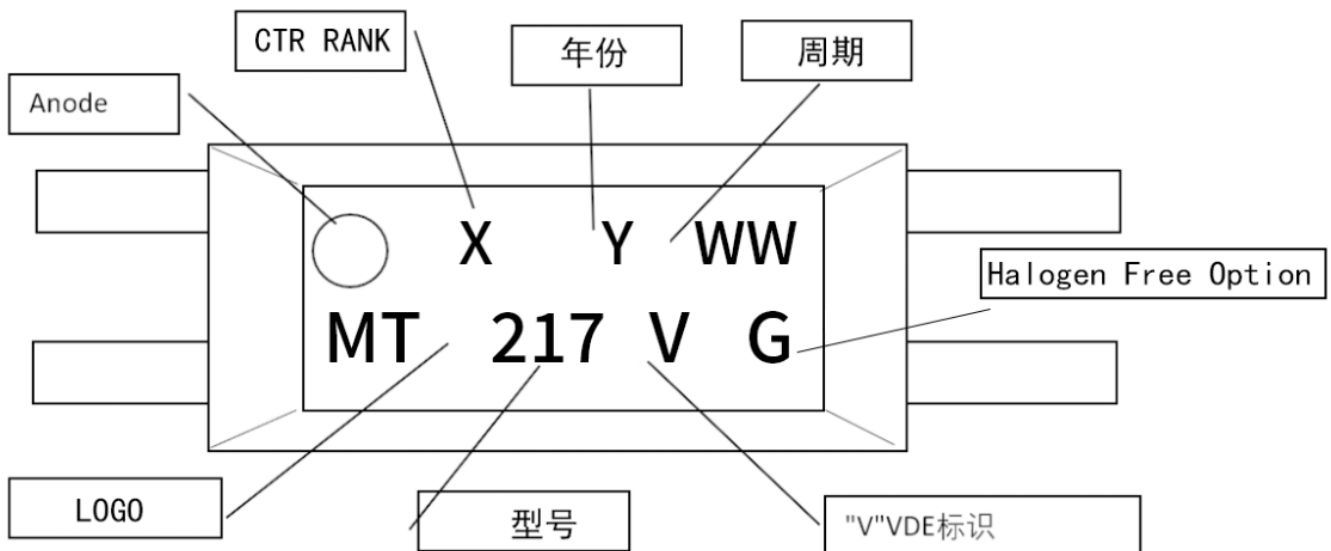
Naming Rule

MT-217-X-Y-WW-V-G

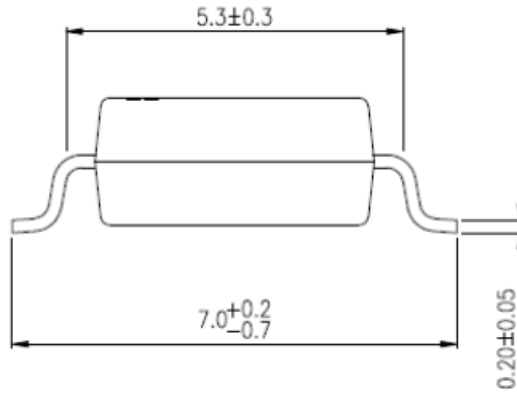
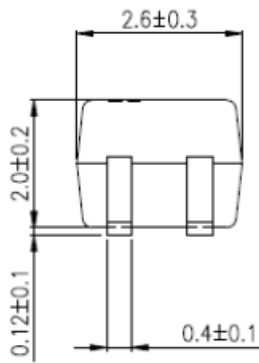
- MT---Logo
- 217---Part Number
- (X)--- Representative: ABCD
- (Y)---Product Year
- (WW)---product lifecycle
- (V)---VDE
- (G)---halogen-free

Example:MT-217-X-Y-WW-V-G

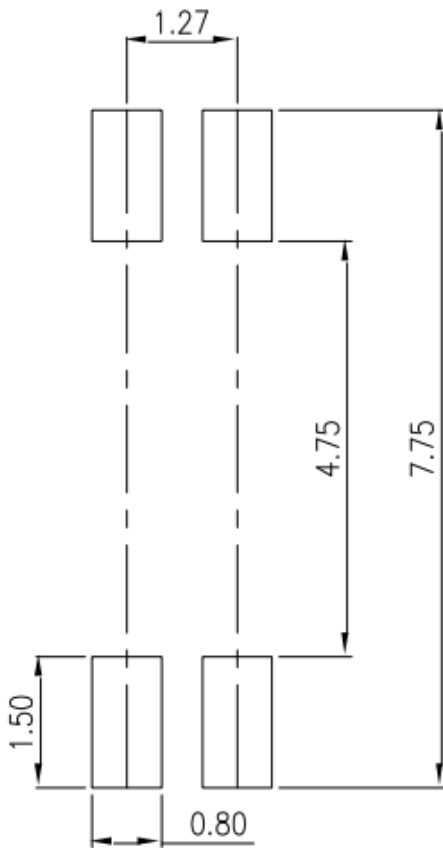
Markingx



Package Dimensions

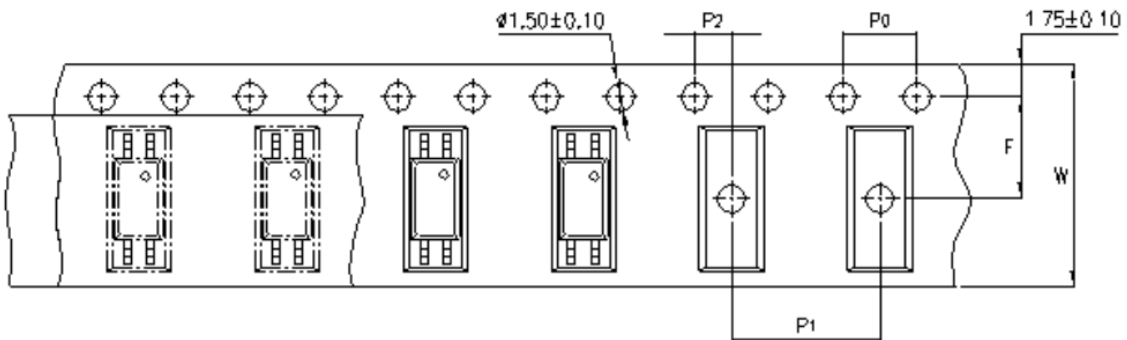


Surface mount (Footprint Dimensions)

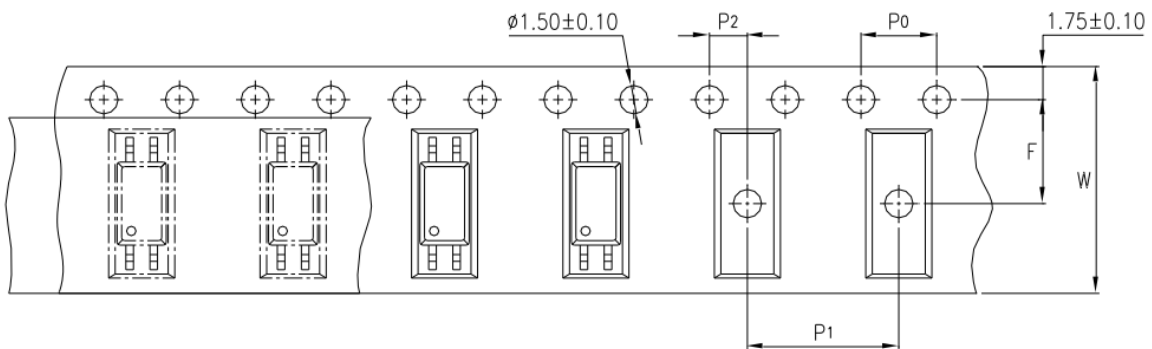


Carrier Tape Specifications

- “TP1” Tape (3000 units per reel)

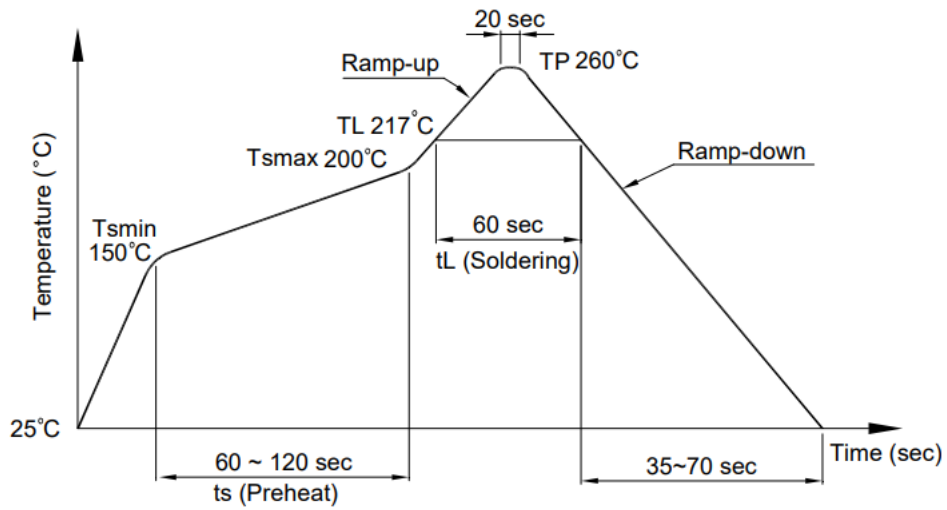


- “TP” Tape (3000 units per reel)



| Symbol | Description | Dimensions in mm (inches) |
|----------------|--|---------------------------|
| W | Tape wide | 12±0.3 (0.472) |
| P ₀ | Pitch of sprocket holes | 4±0.1 (0.157) |
| F | Distance of compartment | 5.5±0.1 (0.217) |
| P ₂ | | 2±0.1 (0.079) |
| P ₁ | Distance of compartment to compartment | 8±0.1 (0.315) |

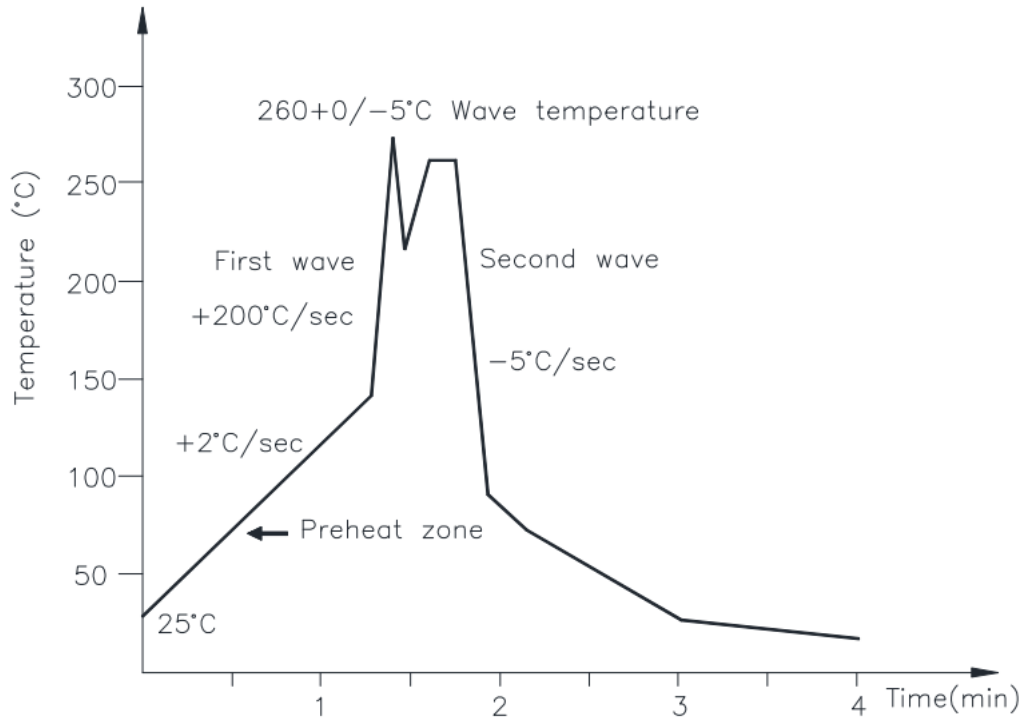
Solder Reflow Temperature Profile (JEDEC-STD-020C compliant)



| Profile Item | Conditions |
|--|---------------|
| Preheat | |
| - Temperature Min (T _{Smin}) | 150°C |
| - Temperature Max (T _{Smax}) | 200°C |
| - Time (min to max) (ts) | 90±30 sec |
| Soldering zone | |
| - Temperature (T _L) | 217°C |
| - Time (t _L) | 60 ~ 100 sec |
| Peak Temperature (T _P) | 260°C |
| Ramp-up rate | 3°C / sec max |
| Ramp down rate | 3~6°C / sec |

One time soldering reflow is recommended within the condition of temperature and time profile shown
Do not solder more than three times

Wave Soldering (JEDEC22A111 compliant)



One time soldering is recommended within the condition of temperature

Temperature: 260+0/-5°C

Time: 10 sec

Preheat temperature: 25 to 140°C

Preheat time: 30 to 80 sec